

Product / Process Change Notification



N° 2015-011-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Implementation of 300mm wafer diameter and capacity extension for CoolMOS™ 600V CP and conversion to halogen free mold compound for DPAK

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **13. April 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
- This PCN includes a **Product Discontinuation Notice** (JEDEC STANDARD "JESD48") on page 4/4

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted. In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

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SUBJECT OF CHANGE:

- Implementation of 300mm wafer diameter.
- Extension of wafer production capacity.

PRODUCTS AFFECTED: Please refer to 1_cip_2015-011_a

REASON OF CHANGE: Capacity Extension for 300mm wafer production

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
<ul style="list-style-type: none"> ■ Wafer production site with wafer diameter: 	Infineon Technologies (Kulim) Sdn. Bhd., Malaysia (200mm)	Infineon Technologies (Kulim) Sdn. Bhd., Malaysia (200mm) Infineon Technologies Dresden GmbH, Germany (300mm) Infineon Technologies Austria AG, Villach, Austria (300mm)
<ul style="list-style-type: none"> ■ TO220 FP Back End Location 	Nantong Fujitsu Microelectronics Co., Ltd. (NFME), China ASE (Weihai) Inc., China PSI, Philippines	Nantong Fujitsu Microelectronics Co., Ltd. (NFME), China ASE (Weihai) Inc., China
<ul style="list-style-type: none"> ■ DPAK Halogen Free Production: 	Halogen free production at: IFX Malacca, Malaysia. Non halogen free production at: IFX Malacca, Malaysia Non halogen free production at: Nantong Fujitsu Microelectronics Co., Ltd. (NFME), China	Halogen free production at: IFX Malacca, Malaysia Halogen free production at: Nantong Fujitsu Microelectronics Co., Ltd. (NFME), China

PRODUCT IDENTIFICATION:

1. Internal traceability: assured via baunumber, lotnumber and date code

2. External traceability: new SP number for Halogen free products

3. Lotnumber printed on Barcode Product Label:

1Exxxxxx = IFX Kulim, 200mm production

PFxxxxxx = IFX Kulim, 200mm production

ZFxxxxxx = IFX Dresden, 300mm production

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TIME SCHEDULE:

■ Final qualification report:	2_cip_2015-011_a	
■ First samples available:	February 2016	
■ Intended start of delivery:	May 2016 or earlier date if customers accepted the change	
■ Last order date of unchanged product:	15 th August 2016	See page 4/4
■ Last delivery date of unchanged product:	15 th February 2017	See page 4/4

ASSESSMENT:

Product Quality and Reliability remains the same as proven by product and wafer technology qualification. Product data sheets with all electrical characteristics remain unchanged.

Processes are optimized to meet identical product performance according to the existing Infineon specifications.

DOCUMENTATION:

1_cip_2015-011_a	List of affected products and details in changes per product
2_cip_2015-011_a	Final qualification report

PRODUCT DISCONTINUATION

PD15011



Referring to PCN N° 2015-011-A

■ Last order date of unchanged product:	15 th August 2016
■ Last delivery date of unchanged product	15 th February 2017

DISCONTINUED				NEW (REPLACEMENT)			
Device	SP N°	OPN	Package	Device	SP N°	OPN	Package
IPD60R385CP	SP000307381	IPD60R385CPBTMA1	PG-TO252-3	IPD60R385CP	SP000680638	IPD60R385CPATMA1	PG-TO252-3
IPD60R385CP E8177	SP000680588	IPD60R385CPE8177ATMA1	PG-TO252-3	IPD60R385CP	SP000680638	IPD60R385CPATMA1	PG-TO252-3

If you have any questions, please do not hesitate to contact your local Sales office.

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 extension for
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Sales Name	Current SP number	OPN	Package
IPA60R125CP	SP000095275	IPA60R125CPXKSA1	PG-TO220-3
IPA60R165CP	SP000096437	IPA60R165CPXKSA1	PG-TO220-3
IPA60R199CP	SP000094146	IPA60R199CPXKSA1	PG-TO220-3
IPA60R250CP	SP000310226	IPA60R250CPXKSA1	PG-TO220-3
IPA60R299CP	SP000096438	IPA60R299CPXKSA1	PG-TO220-3
IPA60R385CP	SP000089316	IPA60R385CPXKSA1	PG-TO220-3
IPD60R385CP	SP000307381	IPD60R385CPBTMA1	PG-TO252-3
IPD60R385CP	SP000680638	IPD60R385CPATMA1	PG-TO252-3
IPD60R385CP E8177	SP000680588	IPD60R385CPE8177ATMA1	PG-TO252-3
IPI60R099CP	SP000297356	IPI60R099CPXKSA1	PG-TO262-3
IPI60R125CP	SP000297355	IPI60R125CPXKSA1	PG-TO262-3
IPI60R165CP	SP000680744	IPI60R165CPXKSA1	PG-TO262-3
IPI60R199CP	SP001109508	IPI60R199CPXKSA2	PG-TO262-3
IPI60R385CP	SP000103250	IPI60R385CPXKSA1	PG-TO262-3
IPP60R099CP	SP000057021	IPP60R099CPXKSA1	PG-TO220-3
IPP60R125CP	SP000088488	IPP60R125CPXKSA1	PG-TO220-3
IPP60R165CP	SP000084279	IPP60R165CPXKSA1	PG-TO220-3
IPP60R199CP	SP000084278	IPP60R199CPXKSA1	PG-TO220-3
IPP60R250CP	SP000358136	IPP60R250CPXKSA1	PG-TO220-3
IPP60R299CP	SP000084280	IPP60R299CPXKSA1	PG-TO220-3
IPP60R385CP	SP000082281	IPP60R385CPXKSA1	PG-TO220-3